Layer Name	Туре	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric 1	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.6000 mm

Board overall dimensions: 19.0500 mm x 50.7951 mm

Min track/spacing: 0.0000 mm / 0.2540 mm Min hole diameter: 0.3000 mm Copper Finish: HASL Impedance Control: No No

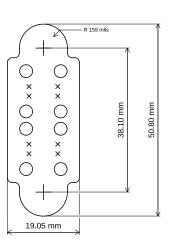
Castellated pads: No Plated Board Edge: No Edge card connectors:

Outer Copper Weight: 1 oz Via type: Tented

LAYERS

User.1

Edge.Cuts



NOTES

1.Layers: 2 2.Thickness: 1.6 3.Surface finish: HASL 4.Outer Copper Weight: 1oz 5 Via covering: Tented 6.Min hole size: .3mm 7.Gold Fingers: No 8.Castellated Holes: No 9 Edge Plating: No

Drill Map:

× 1.092mm / 0.0430" (8 holes) O 3.404mm / 0.1340" (8 holes) (not plated) + 4.039mm / 0.1590" (2 holes) (not plated)



971 SPARTAN ROBOTICS

Sheet: File: TEE-CAN-SL.kicad_pcb

Title: TEE CAN SL

Size: B Date: 2024-10-12 KiCad E.D.A. 8.0.5 Rev: R4 Page: 1/1